

Atty. Docket No.: 0941-0411P

Page 1 of 1

101995233	JVEK SHEET
	ner of Patents and Trademarks: ginal documents or copy thereof.
1. Name of conveying party(ies):	2. Name and address of receiving party(ies)
[FAMILY NAME (ALL CAPS), Given Name]	Name: SILICON INTEGRATED SYSTEMS CORP.
NIEN, Chun-Feng 2-19.02	Internal Address:
	Internal Address: Street Address: No. 16, Creation Rd. 1, Science-Based Industrial Park City: Hsin Chu State: 7IP:
Additional name(s) of conveying party(ies) attached? YES NO	City: Hsin Chu State: ZIP:
3. Nature of conveyance:	Country: TAIWAN, R.O.C. Postal Code:
	Additional name(s) & address(es) attached? YES NO
Security Agreement Change of Name	
Other:	
Execution Date: January 9, 2002	
4. Application number(s) or patent number(s):	
If this document is being filed together with a new application, the	e execution date of the application is: January 9, 2002
A. Patent Application No(s). 10, 076 39 5 NEW	B. Patent No.(s).
Additional numbers attac	hed? TYES NO
 Name and address of party to whom correspondence concerning document should be mailed: Name: BIRCH, STEWART, KOLASCH & BIRCH, LLP 	6. Total No. of applications/patents involved: ONE (1)
	7. Total fee (37 C.F.R. § 3.41): \$40.00
Street Address: P.O. BOX 747	⊠ Enclosed
City: FALLS CHURCH State: VA ZIP: 22040-0747	Authorized to be charged to deposit account, if no fee attached.
City, PAPILIS CITCHEST States 112	8. Deposit account number: 02-2448
Country: USA	(Attach triplicate copy of this page
	if paying by deposit account)
DO NOT USE	THIS SPACE
9. Statement and signature.	
To the best of my knowledge and belief, the foregoing in	nformation is true and correct and any attached copy is a true
copy of the original document.	\sim
Joe McKinney Muncy, #32,334 Name of Person Signing/Reg. No.	Signature February 19, 2002 Date
Total number of pages including cover sheet, attachments, and document: TWO (2)	

KM/sl

(Rev. 02/11/02)

PATENT REEL: 012603 FRAME: 0105

ASSIGNMENT

WHEREAS, Shyh-Dar LEE and Chun-	Feng NIEN
hereafter referred to as ASSIGNOR, has/have invented cert	
described and set forth in the below identified application f	or United States Letters Patent:
Title: METHOD OF REDUCING MICRO-SCRATCH	HES DURING TUNGSTEN CMP
Filed: February 19, 2002 Serial No.	
Executed on: January 9, 2002	
WHEDEAS Silison Internated Sur	
WHEREAS, <u>Silicon Integrated Systemation Rd. 1, Science-Based Industrial</u>	
R.O.C. hereinafter referred to as ASSIGNEE, is de	
interest in the said invention and application and in any	
granted on the same;	
NOW, THEREFORE, TO ALL WHOM IT MAY	CONCERN: Do it known that for
good and valuable consideration, receipt of which is h	
Assignor has/have sold, assigned and transferred, and by the	
transfer unto the said Assignee, and Assignee's successors	
title and interest in and to the said invention and applic	cation and all future improvements
thereon, and in and to any Letters Patent which may here	
United States, the said interest to be held and enjoyed by sa	
as it would have been held and enjoyed by said Assignor h	
been made, to the full end and term of any Letters Patent any division, renewal, continuation in whole or in par	
prolongation or extension thereof.	t, substitution, conversion, reissue,
•	21 24 4 1 414
Assignor further agrees/agree that he/she/th	ey will, without charge to said
Assignee, but at Assignee's expense, cooperate with A application and/or applications, execute, verify, acknow	ledge and deliver all such further
papers, including applications for Letters Patent and for the	e reissue thereof, and instruments of
assignment and transfer thereof, and will perform such of	ther acts as Assignee lawfully may
request, to obtain or maintain Letters Patent for said inve	ntion and improvement, and to vest
title thereto in said Assignee, or Assignee's successors and	assigns.
BY TECTIMONIV WHEREOF Assignor has/have	signed his/her/their name(s) on the
IN TESTIMONY WHEREOF, Assignor has/have signed his/her/their name(s) on the date(s) indicated.	
date(s) marcuted.	
	1/1/02
S.D.Le	1/1/62
Shyh-Dar Lee	Date:
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Fora XIsela	1/0/02
Chun-Feng Nich	
Chun-Feng NIEN	Date:

90P105/0702-7363US

RECORDED: 02/19/2002